Ritsumeikan Asia Pacific University, 3 March 2010 Strategic Roadmapping Aligning technology, products and markets for strategy and innovation Dr Robert Phaal **Centre for Technology Management University of Cambridge**

IfM research

Policy







International Manufacturing



Strategy and Performance



Technology Management



Industrial Sustainability



Service and Support



Distributed Information and Automation

Technology

Management



Production Processes

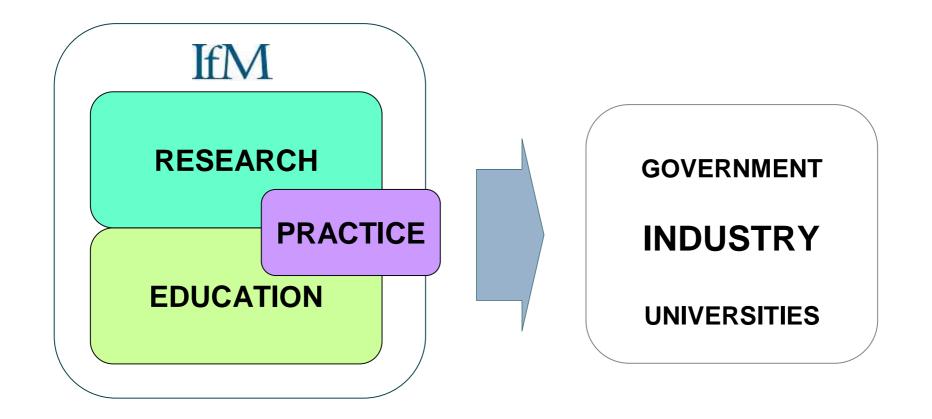


Industrial Photonics





Approach









- Overview of roadmapping
- 'Fast-start' workshop methods
- Current research: navigating industrial emergence
- Summary & questions / discussion

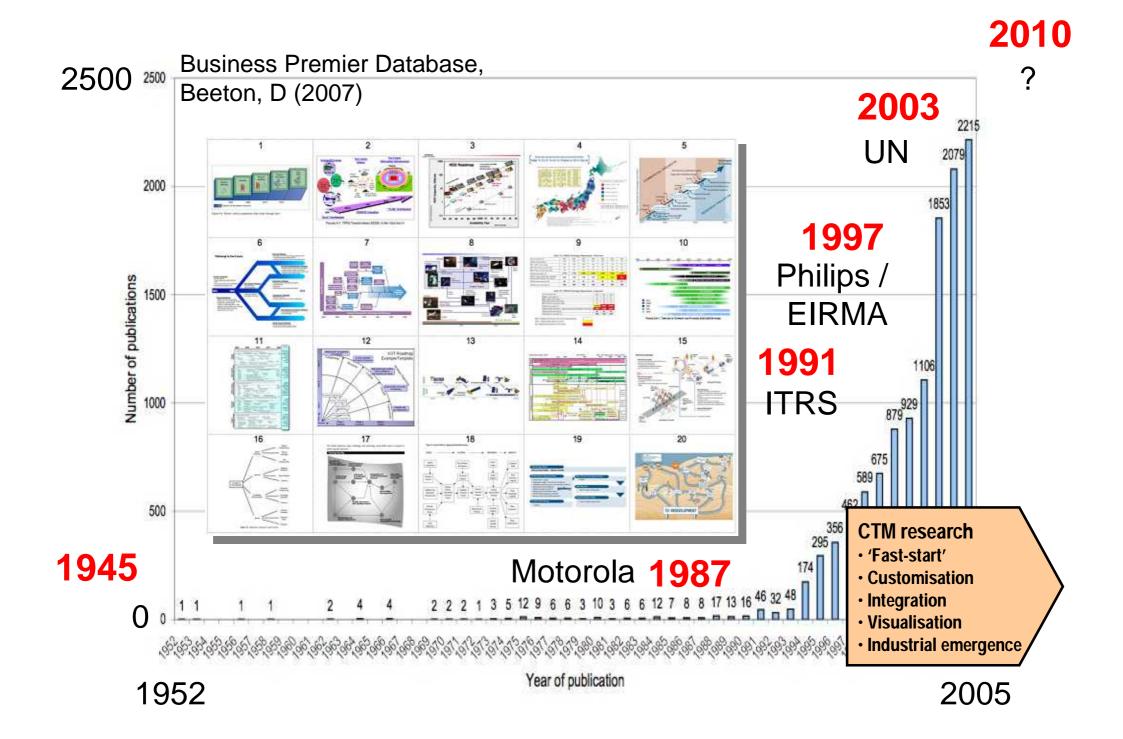




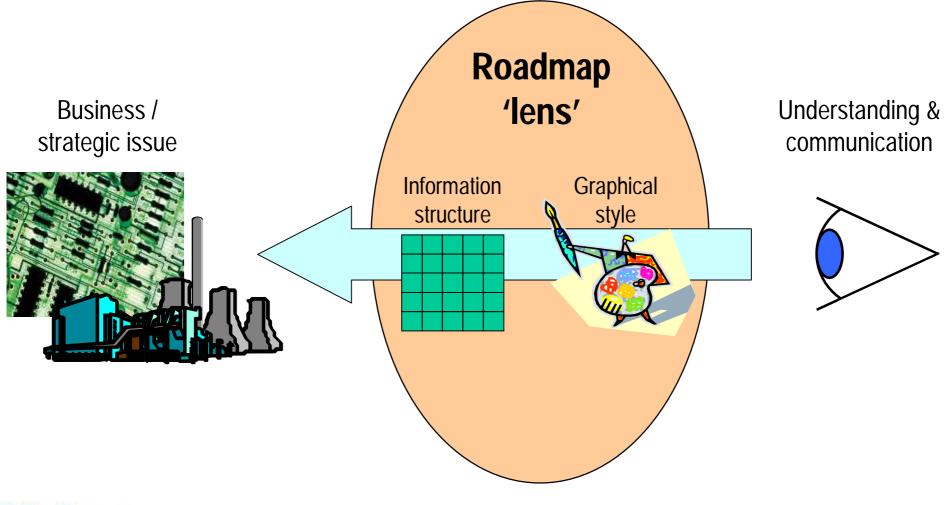
Overview of roadmapping







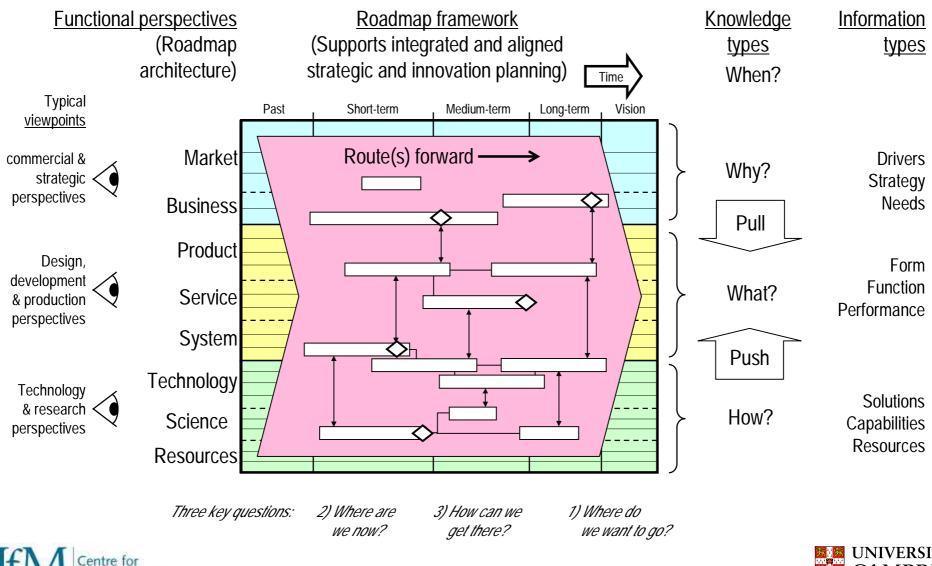
Roadmaps as 'strategic lenses'







Roadmaps combine multiple perspectives





Technology Management

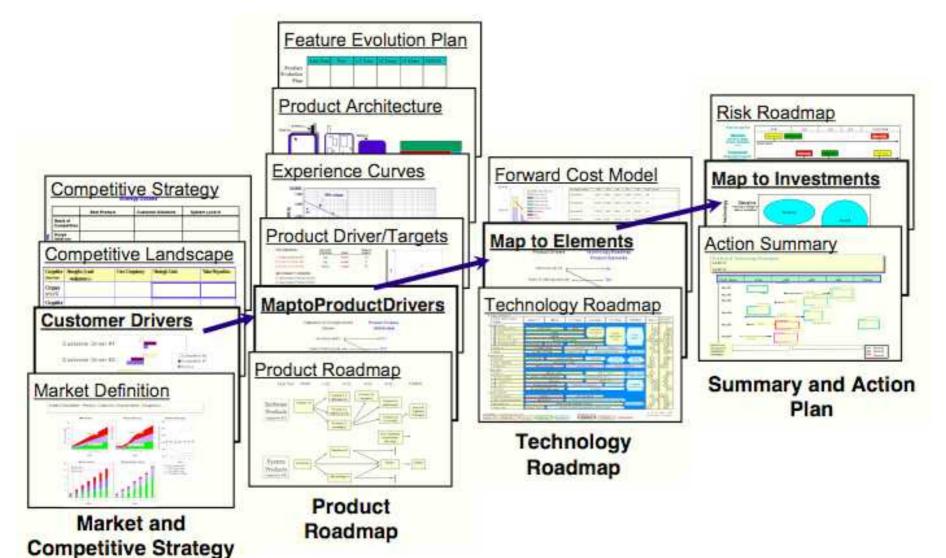


Roadmaps provide a common visual language for strategy and innovation **Process funnel (e.g. strategy, new product development)** Market-Technology, Summary-Detail Iteration **Requirements fluid** Effort **Concepts fuzzy Requirements clear**, stable Many unknowns Time **Concepts clear, stable** Many options Fewer unknowns, risks understood Many assumptions Fewer options, greater constraints Few constraints **Scenarios** ??? ? ? → Convergent process Divergent process – → Plan → Implement Centre for

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Lucent Technologies technology roadmapping approach



Source: Richard Albright The Albright Strategy Group, www.albrightstrategy.com





Lucent Technologies technology roadmap

Core technology Area	Last Yr	Now	+1 Year	+2 Year	+3 Year	VISION	Import.	Compet Position
eight/size							1	1
1 Interface ASIC	5735 0	hip	ACA	Integrated	\square		167	CF
Interface ASIC DSP		1832		Call signal	Single	/		CF
Audio codec		CMOS		proc.	Baseband	"Soft Radio"	G	CF
Audio codec Audio front end Microcontroller		Bipolar	discretes		Chip	1 1000	Cic	CIF
Microcontroller	(8 bit CISC)	16 bit CISC	microco	ontroller			CE	CE
Housing	1.7mm t	hick	1.4mm		1.2mm]	GP_	CA
PWB	6 layer 1.	5mm	6 layer 1mm) 4 layer ().8mm Flex	Molded-in	I CP	CE CE CE
se of use								1
Display	(2-line LCD)	4-lin	e LCD	1/4 VGA	Touch	Voice	B	QE
User interface		Naviga	tion keys	\rightarrow	Sensitive	Interface	CF	CF CF
Software	Menu d	lriven	Config	lurable	Cust. ad	daptive	CF	Œ
alk time								
Battery	\subseteq	NiCd - 4.8V			- 3.6V	Altern. tech.)	B	10
Power supply	Linear - 50%	6 efficient		witching (80% e	eff.)	~100% effic.)	CE	CF)
Power amp	\square	Module		(MMI	C-3V)	\square	FC	BBB
Radio	Triple con	nversion	Double co	onversion	(Homodyne >	(Tunable,)	1 CF	(F)
Antenna	Dual band,	High gain		Diversity	$ \rightarrow $	\ Homodyne		TE
udio quality								
Voice coders	Vcel	p	ITU, Q	celp13			G	CF
DSP noise algorithms	Expan	nder	IS-99 Data B	ER Improvemen	nt/echo cancel.		ICF	CF
Microphone		First	order gradient (FOG)	X	Steering array	G.	CF
Receivers	(Piezoelectric)	N	oise canceling ea	rpiece, miniatur			CF)'	CF)
LEGEND: Technology S	ource.			Funding status:			LM.H.	t. F=futur



Albright & Kappel (2003)



International Technology Roadmap for Semiconductors, 2003

Year of Production	2003	2004	2005	2006	2007	2008	2009
Technology Node		hp90			hp65		
DRAM ½ Puch (nm) [1]		90	80	70	65	57	50
MPU/ASIC Metal 1 (M1) % Pitch (nm)		107	95	85	76	67	60
MPU/ASIC % Ptich (nm)		90	80	70	65	57	50
MPU Printed Gate Length (nm)		53	45	40	35	32	28
MPU Physical Gate Length (nm)		37	32	28	25	22	20
DRAM cell size (µm ²) [2]		0.065	0.048	0.036	0.028	0.019	0.015
DRAM storage cell dielectric: equivalent physical oxide thickness, EOT (nm) [3]		2.3	1.8	1.3	0.8	0.8	0.8
Minimum DRAM retention time (ms) [4]		64	64	64	64	64	64
DRAM soft error rate (FITs) [5]	1000	1000	1000	1000	1000	1000	1000

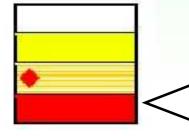
Table 49a DRAM Technology Requirements-Near-term

Table 49b DRAM Technology Requirements-Long-term

Year of Production		2012	2013	2015	2016	2018
Technology Node	hp45		hp3 2		hp22	
DRAM % Puch (nm) [1]		35	32	25	22	18
MPU/ASIC Metal 1 (MI) ½ Ptick (nm)		42	38	30	27	21
MPU/ASIC % Pttch (nm)		35	32	25	22	18
MPU Printed Gate Length (nm)		20	18	14	13	10
MPU Physical Gate Length (nm)		14	13	10	9	7
DRAM cell stze (um ²) [2]		0.0077	0.0061	0.0038	0.0025	0.0016
DRAM storage cell dielectric: equivalent physical oxide thickness, EOT (nm) [3]		0.58	0.53	0.42	0.37	0.25
Minimum DRAM retention time (ms) [4]		64	64	64	64	64
DRAM soft error rate (FITs) [5]	1000	1000	1000	1000	1000	1000

Manufacturable solutions exist, and are being optimized Manufacturable solutions are known Interim solutions are known

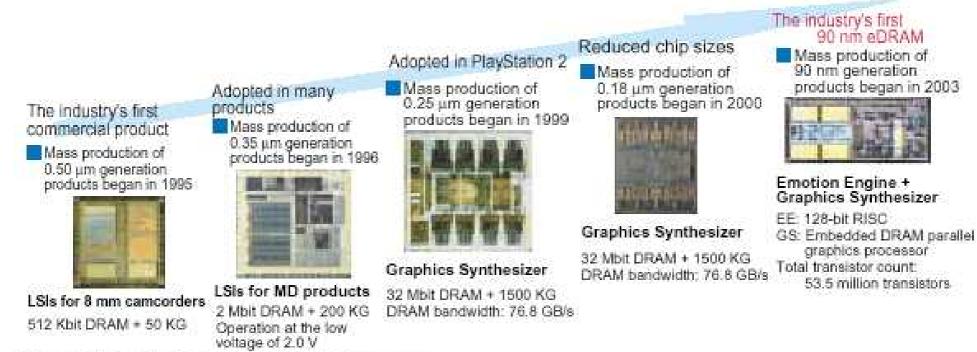
Manufacturable solutions are NOT known



http://public.itrs.net/

'Red brick wall'

Sony DRAM roadmap #1



•Figure 1 Sony's Embedded DRAM Progress

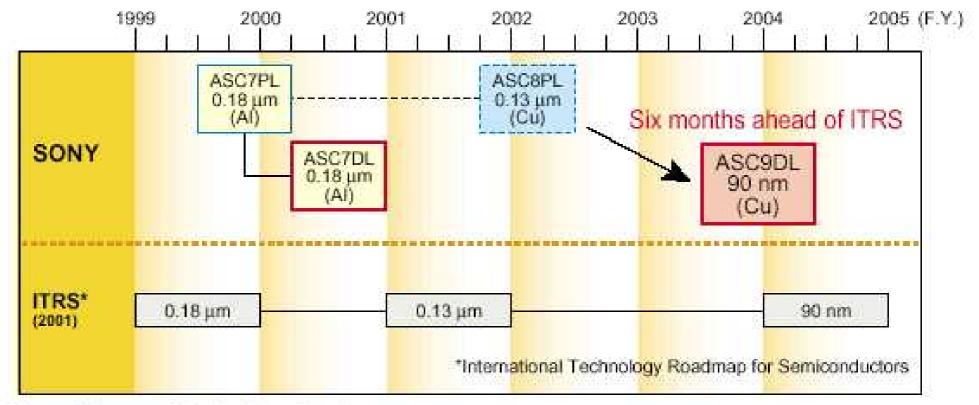
http://www.sony.net/Products/SC-HP/cx_news/vol34/featuring1.html





Sony DRAM roadmap #2

To provide 90 nm technology ahead of the International Technology Roadmap for Semiconductors (ITRS)
 To provide, at the same time, eDRAM technology, which can include high-density DRAM macros



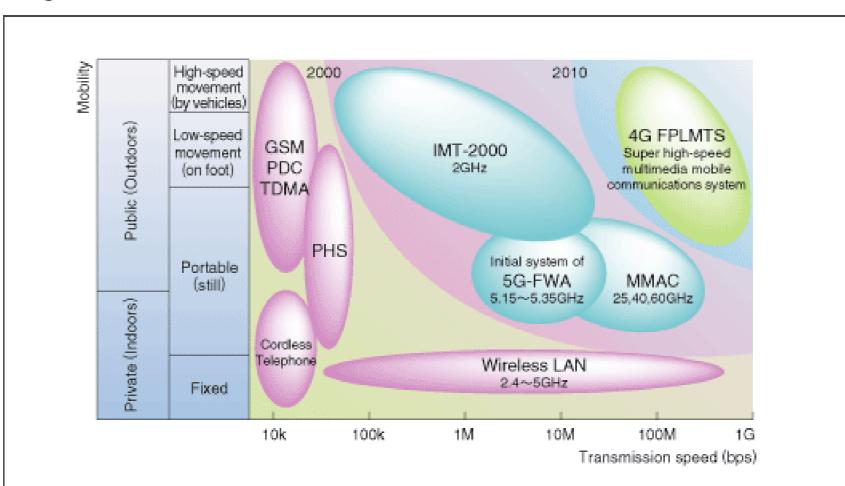
•Figure 2 Process Technology Roadmap

 $http://www.sony.net/Products/SC-HP/cx_news/vol34/featuring1.html$





Panasonic mobile communications roadmap



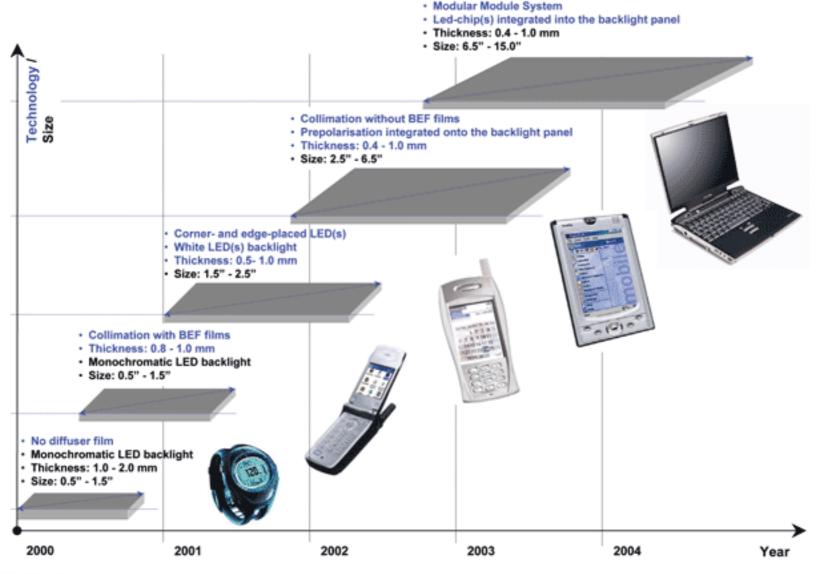
Progress on Mobile Communications Standards

http://panasonic.co.jp/pmc/company/en/cc_0005.html





Roadmap example - display technology

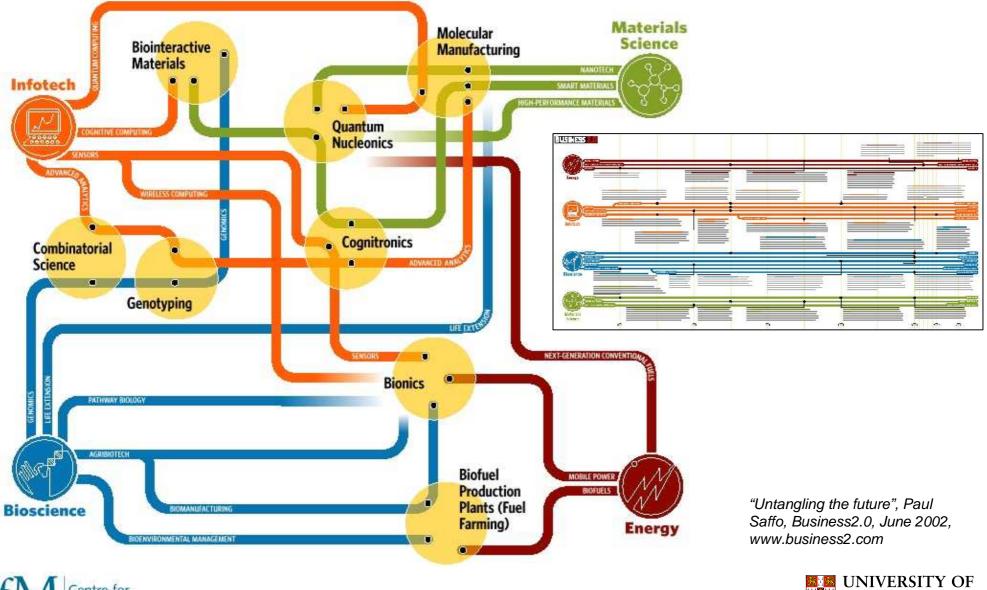


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www.modilis.com/roadmap.htm



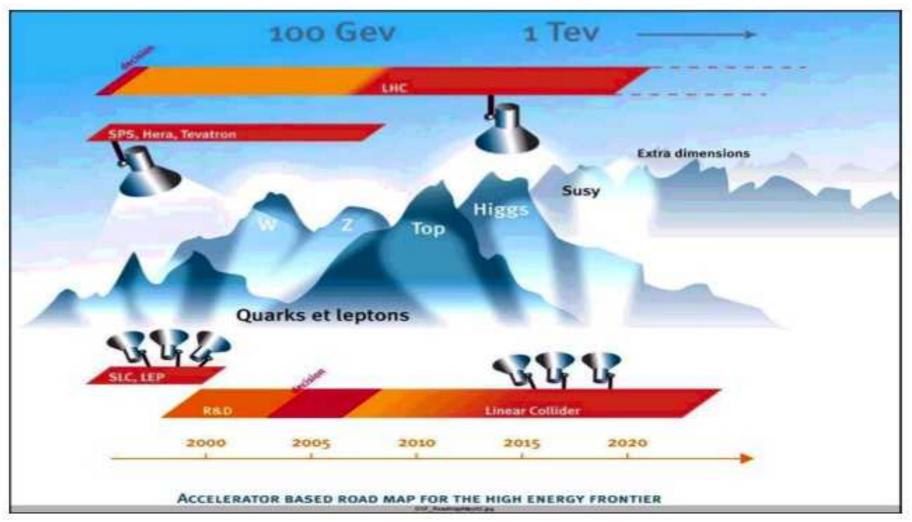
Roadmap example - technology convergence



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CAMBRIDGE

Roadmap example - particle physics



"Particle physics – roadmap to the future", F. Giman, SLAC Summer Institute on Particle Physics, Aug. 2-13 2004.



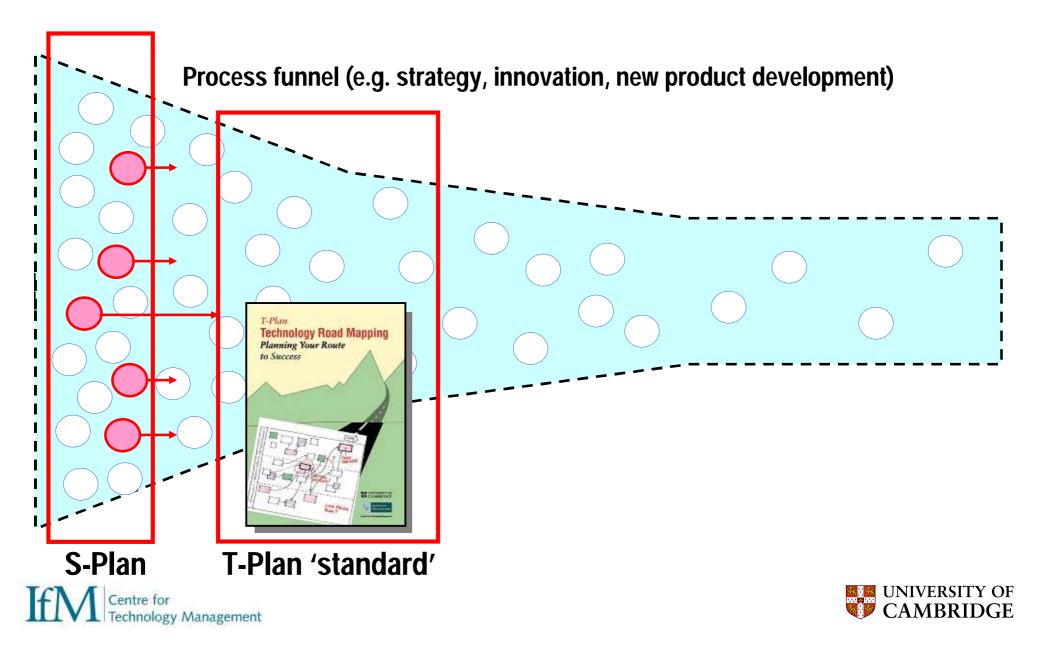


Fast-start workshop methods





Fast-start workshop methods



S-Plan workshop process concept

Step 1: Scan ('Landscape')

- Large group activity
- Broad scope
- Share and capture perspectives
- Link, focus and prioritise

Step 2: Probe ('Landmark')
Small group activity
Focused scope
Share and capture expertise
Organise, plan and action





http://www.foresightvehicle.org.uk/



11-

Foresight Vehicle Technology Roadmap

Technology and Research Directions for Future Road Vehicles

August 2003 Robert 1966, Charles Carbon Roy of Ministry and Antibert 1966, Charles Carbon Roy of Charles Roy Will Still a series that has be

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Version 1.0

http://research.microsoft.com/towards2020science/







23 March 2006 (Vol. 440, No. 7083)

www.nature.com

UK Measurement & Standards for Emerging Technologies (MSET) - 2006

Workshop 1: Transport
Workshop 2: Secure environment
Workshop 3: Sustainable consumption & Production
Workshop 4: Emerging energy technologies
Workshop 5: Healthcare & Bio-science
Workshop 6: Intelligent connected world

Workshop 7: Design Engineering & Advanced manuf'g

Workshop 8: Built Environment

IfM Centre for Technology Management Workshop 9 Cross-cutting Metrology themes & priorities



Japanese METI roadmap







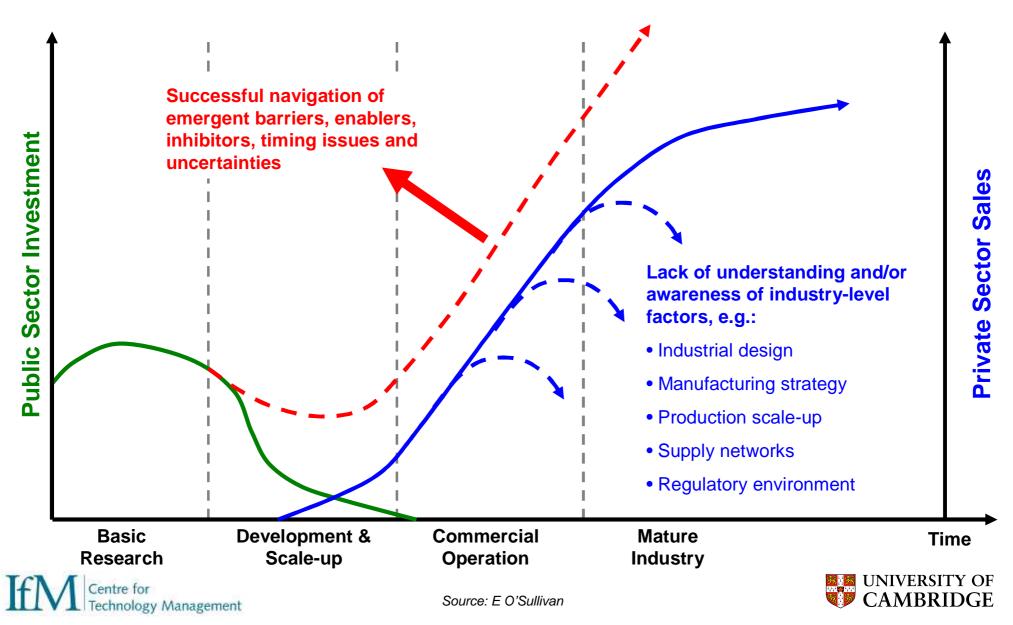
Current research

Navigating industrial emergence





Science-to-industry trajectory



IfM IMRC Emerging Industries Programme (EIP)

Vision

To understand the dynamics of emerging industrial systems in order to enhance the UK's ability to rapidly exploit its scientific and technological capabilities.

Aims

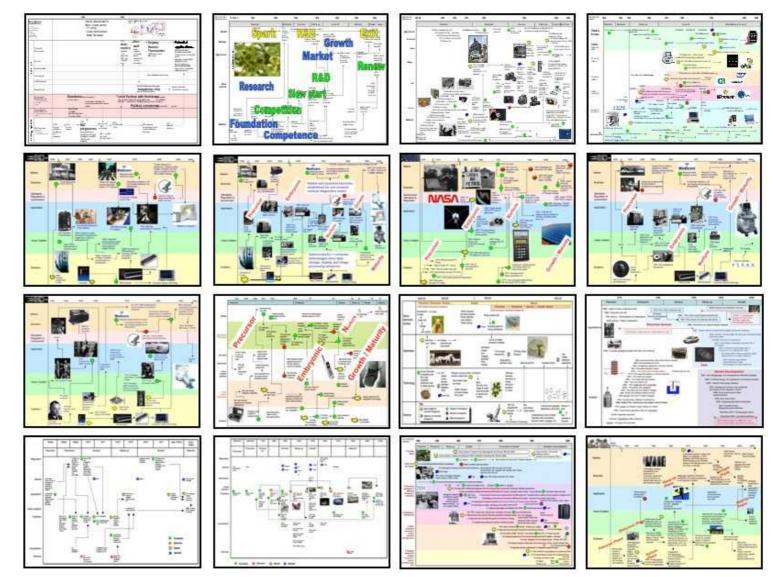
- Support firms navigating the barriers, inhibitors and uncertainties associated with emerging industrial systems
- Support government and public agencies in accelerating the emergence of industries for optimal benefit to the national economy





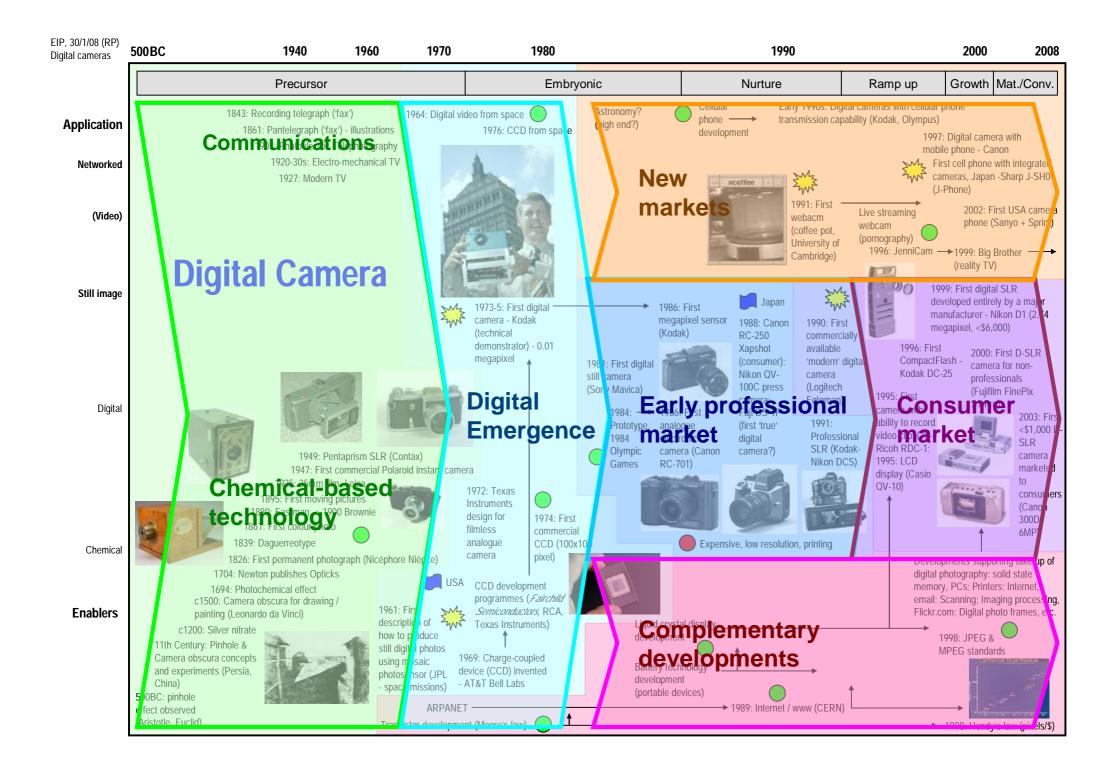
Mapping industrial emergence - learning from history

- Automotive
- Battery
- Catalytic converter
- Cheese
- Computer
- Digital camera
- Displays (TFT-LCD)
- Internet
- Low temp
- Medical imaging
 - MRI
 - Ultrasound
- Tomography
- X-ray
- Mobile phone
- Orthopaedic trauma
- Personal music
- Photovoltaic
- Semiconductors
- Silicon gyro
- Software
- Synthetic diamond
- Wireless

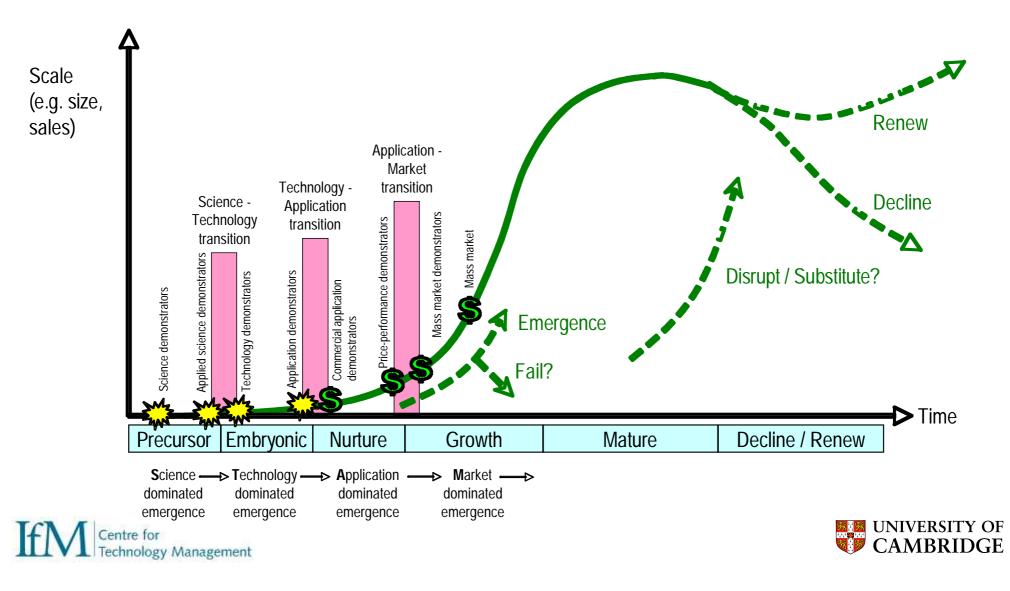




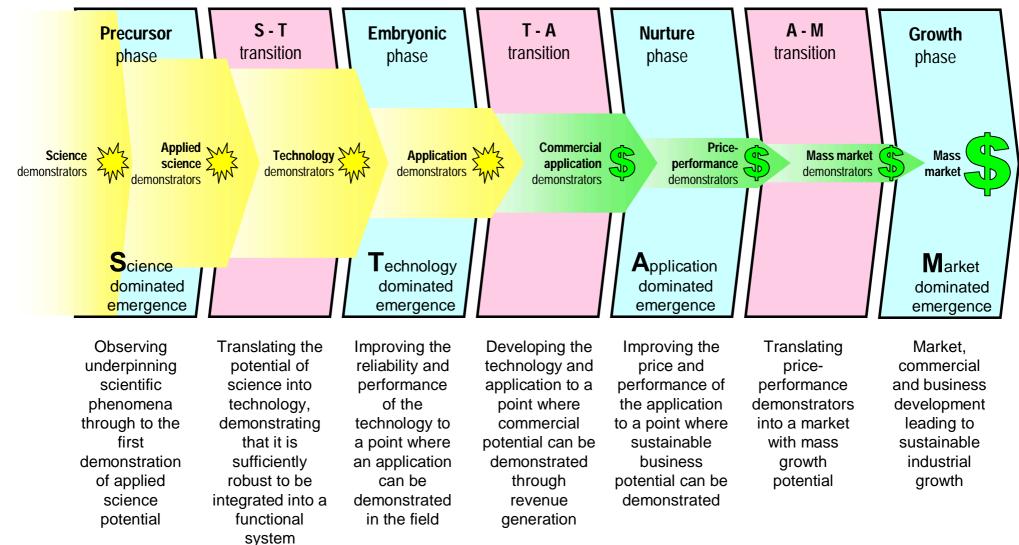




Phase, transitions, milestones and trajectories of industrial emergence



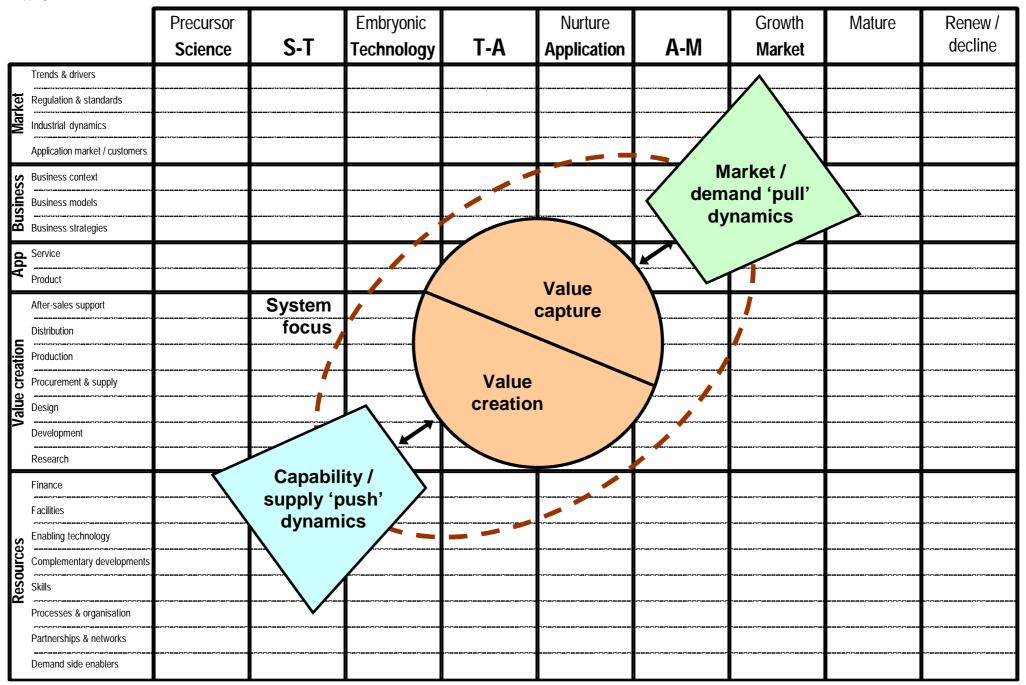
S-T-A-M industrial emergence framework



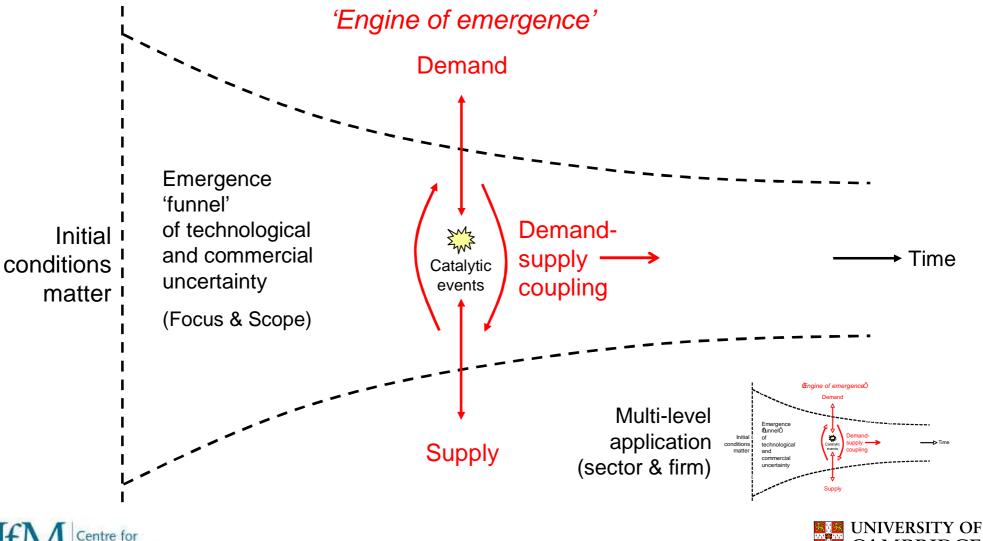




Mapping transitions framework



Principles of industrial emergence



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Way forward

Development and testing of tool modules:

- Environmental scan
- Organisational scan
- Emergence roadmapping
- Investment review guidance

Publications & training

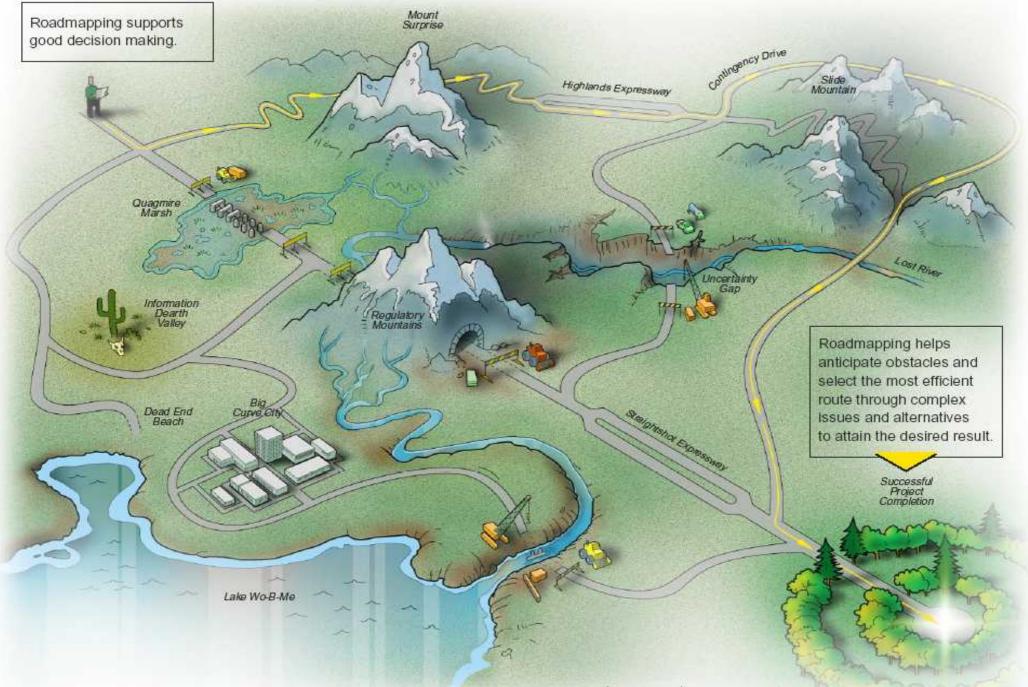




Summary







Idaho National Engineering and Environmental Laboratory, emi-web.inel.gov/roadmap/factsheet.pdf